

# TSD80R850S1/TSU80R850S1

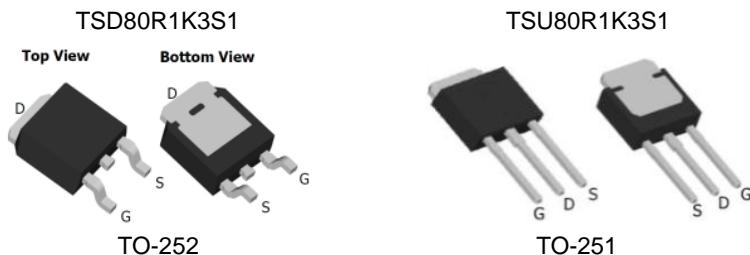
## 800V 6.6A N-Channel SJ-MOSFET

### General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance. This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

### Features

- 850V @ $T_J = 150\text{ }^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 0.75\Omega$
- Ultra Low gate charge (typ.  $Q_g = 25\text{nC}$ )
- 100% avalanche tested



### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	800	V
$I_D$	Drain Current -Continuous ( $TC = 25\text{ }^{\circ}\text{C}$ ) -Continuous ( $TC = 100\text{ }^{\circ}\text{C}$ )	6.6* 4.2*	A
$I_{DM}$	Drain Current – Pulsed (Note 1)	20	A
$V_{GSS}$	Gate-Source voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	86	mJ
$I_{AR}$	Avalanche Current (Note 1)	1.7	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	0.2	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	15	V/ns
$P_D$	Power Dissipation ( $TC = 25\text{ }^{\circ}\text{C}$ ) -Derate above $25\text{ }^{\circ}\text{C}$	63	W W/ $^{\circ}\text{C}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^{\circ}\text{C}$

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2.0	$^{\circ}\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	$^{\circ}\text{C}/\text{W}$

## Electrical Characteristics TC = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ C$	800	--	--	V
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^\circ C$	--	850	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$ , Referenced to 25°C	--	0.6	--	V/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 800V, V_{GS} = 0V$ $T_C = 25^\circ C$	--	--	1	$\mu A$
		$V_{DS} = 640V, V_{GS} = 0V$ $T_C = 150^\circ C$	--	10	--	$\mu A$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	3.5	4.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 3.5A$	--	0.75	0.85	$\Omega$
$g_{FS}$	Forward Trans conductance	$V_{DS} = 40V, I_D = 3.5A$ (Note 4)	--	6	--	S
Dynamic Characteristics						
$C_{iss}$	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	--	320	--	pF
$C_{oss}$	Output Capacitance		--	75	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	5	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400V, I_D = 3.5A$ $R_G = 20\Omega$ (Note 4, 5)	--	13	--	ns
$t_r$	Turn-On Rise Time		--	10	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	85	--	ns
$t_f$	Turn-Off Fall Time		--	14	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 480V, I_D = 3.5A$ $V_{GS} = 10V$ (Note 4, 5)	--	25	--	nC
$Q_{gs}$	Gate-Source Charge		--	2.0	--	nC
$Q_{gd}$	Gate-Drain Charge		--	2.7	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
$I_s$	Maximum Continuous Drain-Source Diode Forward Current	--	--	7	--	A
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	20	--	A
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_F = 2A$	--	0.9	1.5	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_F = 2A$ $di_F/dt = 100A/\mu s$ (Note 4)	--	190	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	2.3	--	$\mu C$

### NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $I_{AS}=1.7A, V_{DD}=50V$ , Starting  $TJ=25^\circ C$
3.  $I_{SD}\leq 6.6A, di/dt \leq 200A/\mu s, V_{DD} \leq BV_{DSS}$ , Starting  $TJ = 25^\circ C$
4. Pulse Test: Pulse width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$
5. Essentially Independent of Operating Temperature Typical Characteristics

# Typical Performance Characteristics

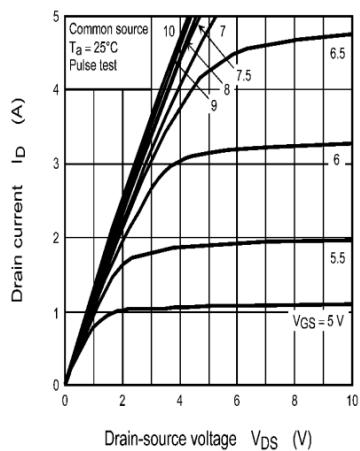


Figure 1: On-Region Characteristics@25° C

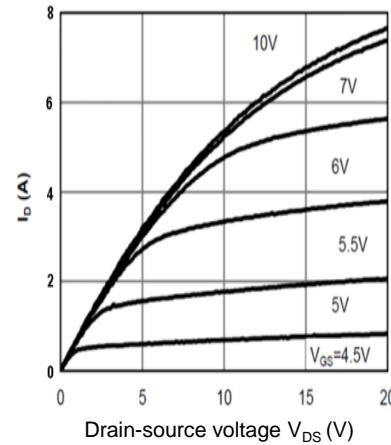


Figure 2: On-Region Characteristics@125° C

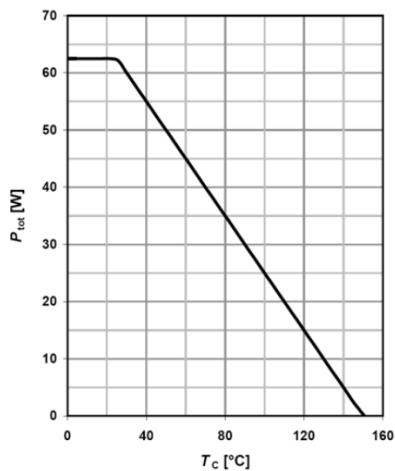


Figure 3:Power Dissipation

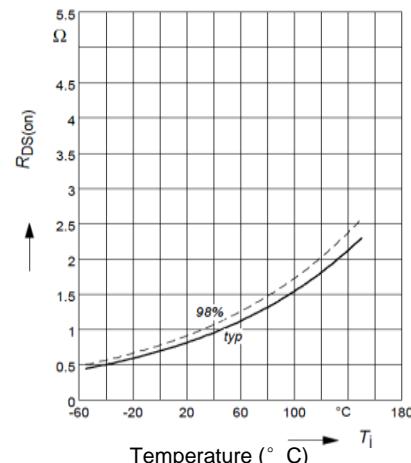


Figure 4: On-Resistance vs. Junction Temperature

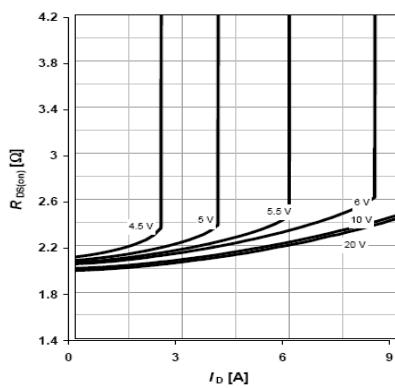
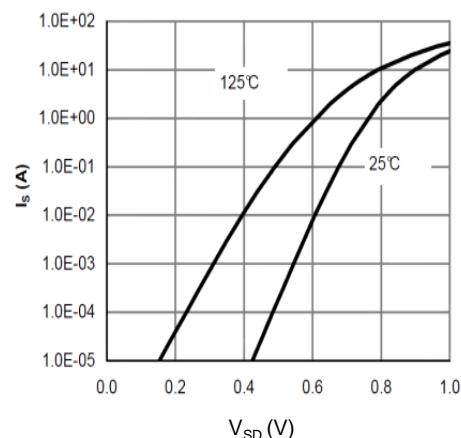
Figure 5 : On-Resistance vs. Drain Current, T<sub>j</sub>=150° C

Figure 6: Body-Diode Characteristics

# Typical Performance Characteristics

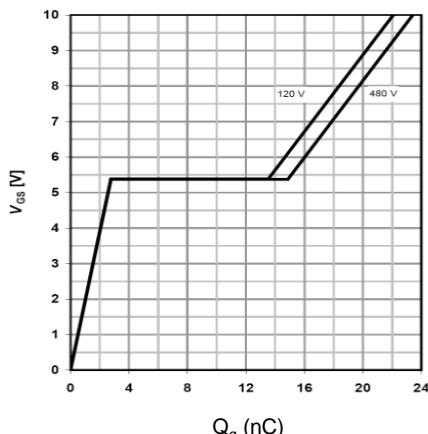


Figure 7: Gate-Charge Characteristics

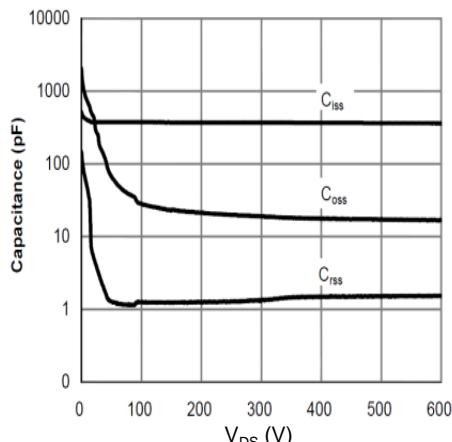


Figure 8: Capacitance Characteristics

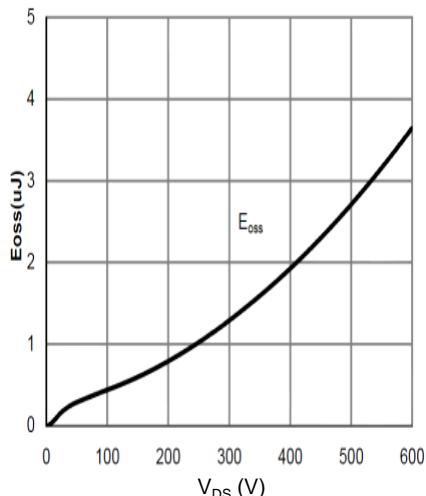
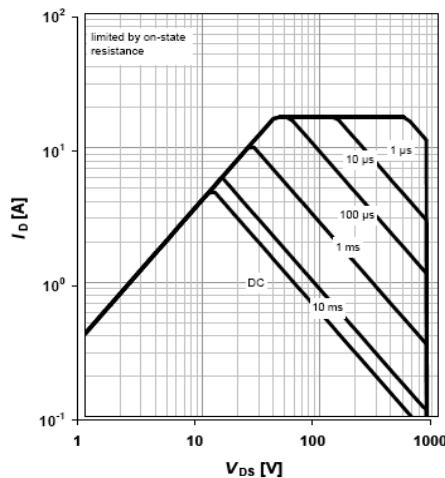
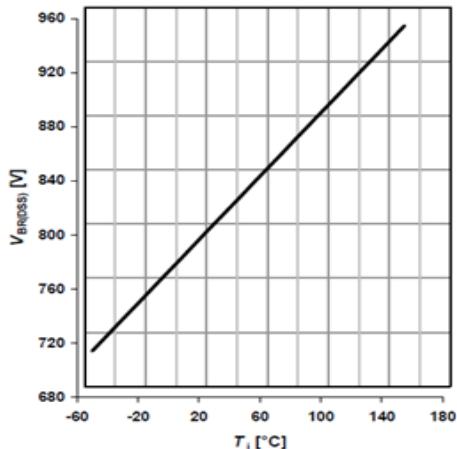
Figure 9:  $C_{oss}$  stored EnergyFigure 10: Maximum Forward Biased Safe Operating Area  
 $T_c=25^\circ\text{ C}$ 

Figure 11: Break Down vs. Junction Temperature

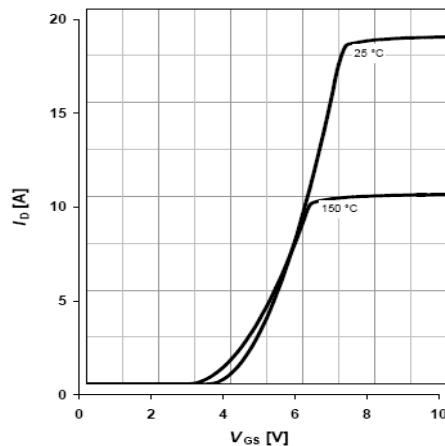


Figure 12: Typical transfer characteristics

## Typical Performance Characteristics

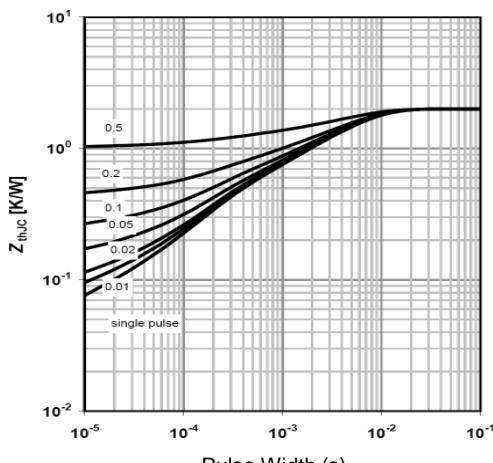


Figure 13: Maximum Transient Thermal Impedance

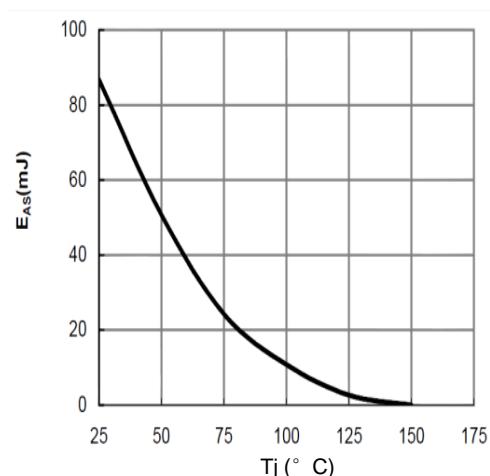


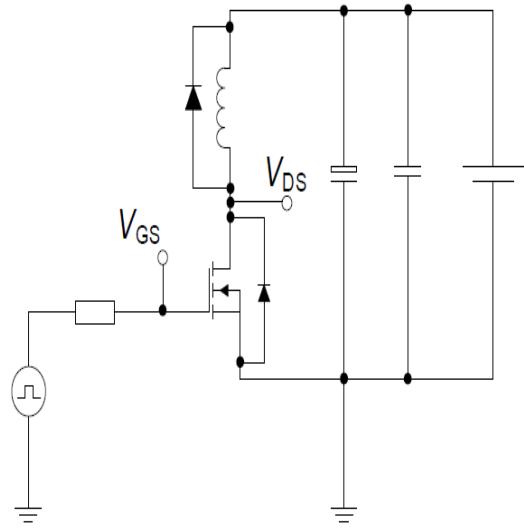
Figure 14: Avalanche energy

# Test circuits

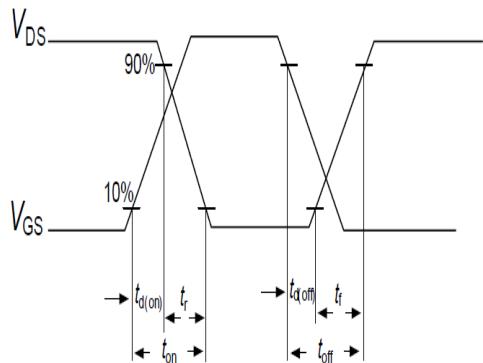
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## Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

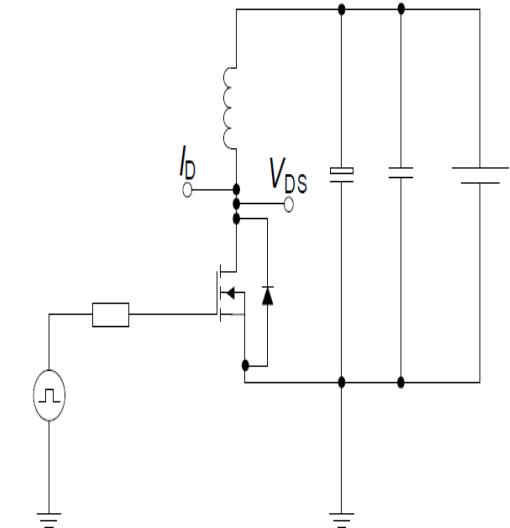


Switching time waveform

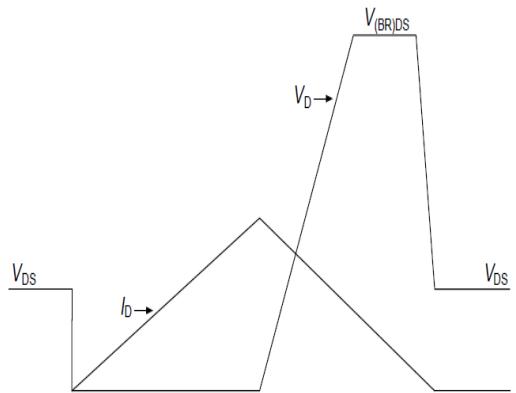


## Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit



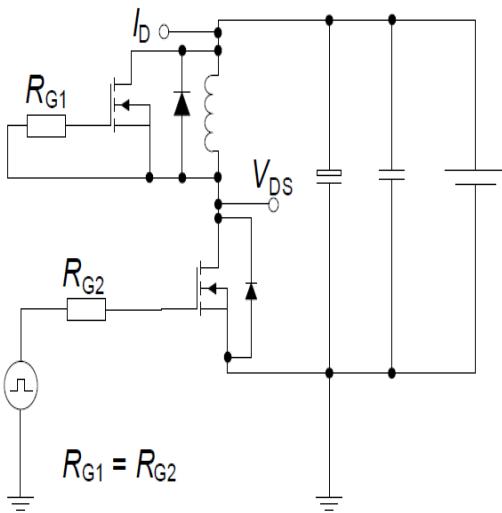
Unclamped inductive waveform



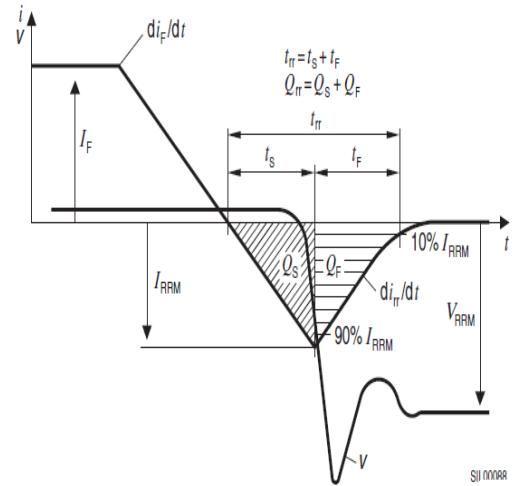
# Test circuits

## Test circuit and waveform for diode characteristics

Test circuit for diode characteristics

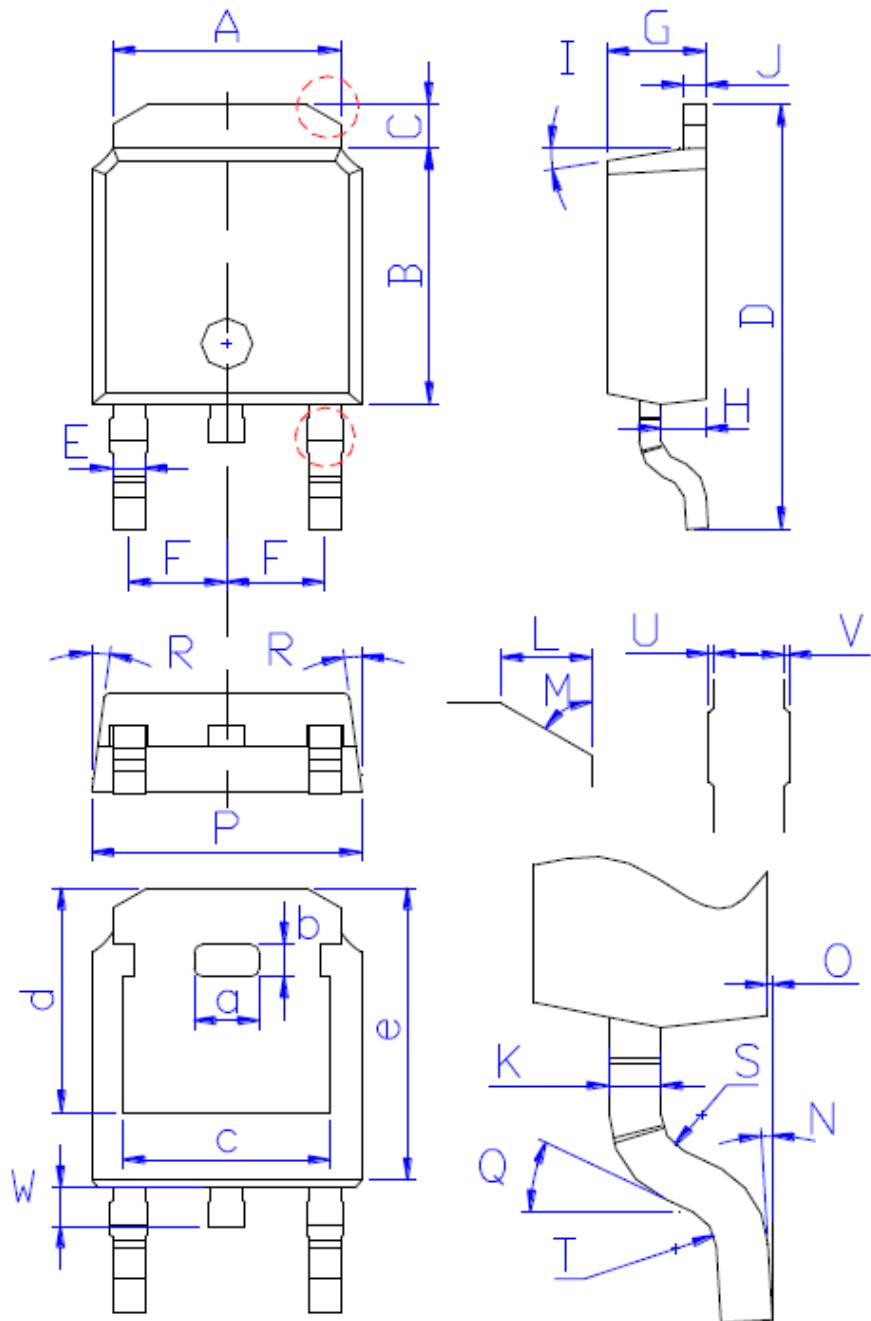


Diode recovery waveform



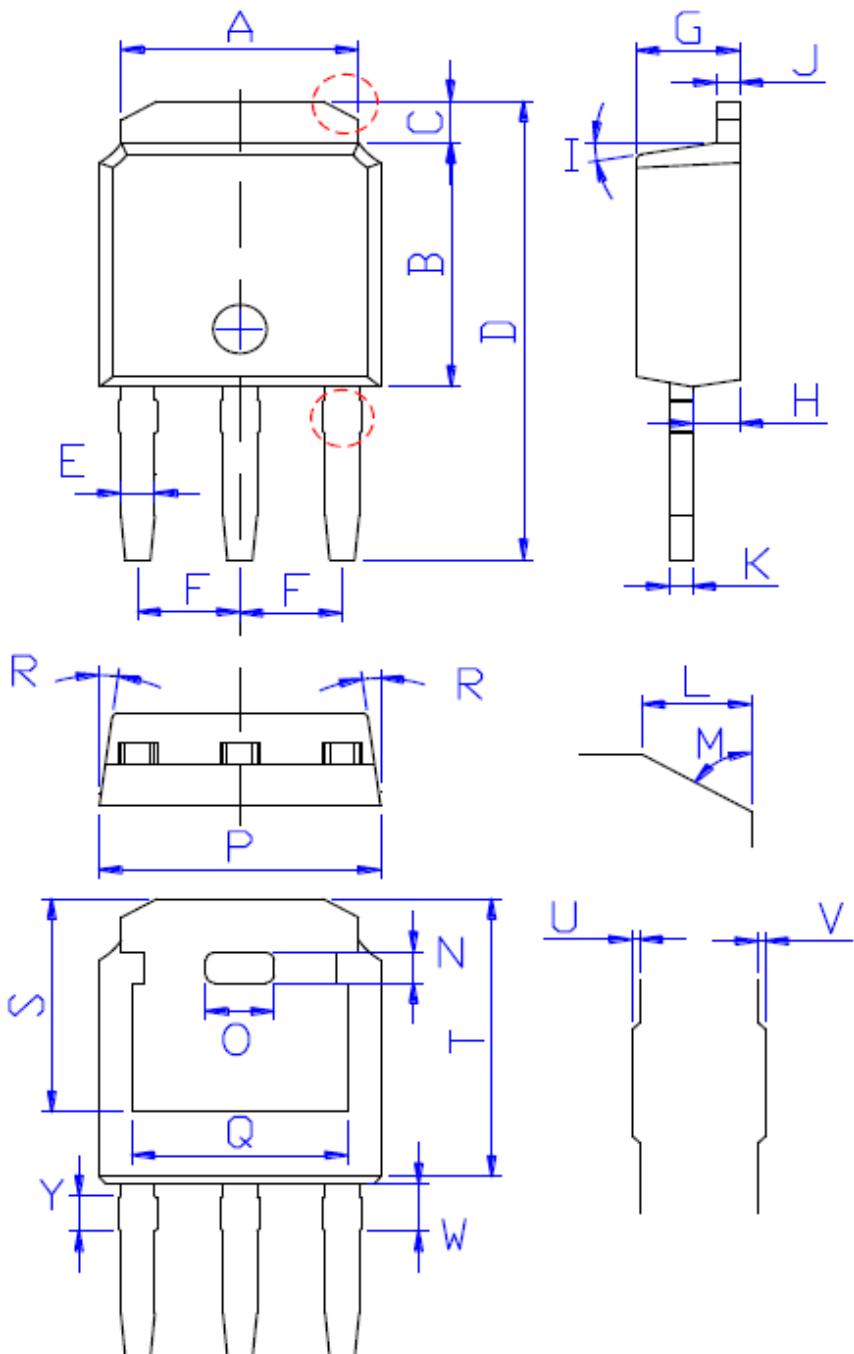
# Package Outline TO-252

TSD80R850S1/TSU80R850S1 800V 6.6A N-Channel SJ-MOSFET



DIM	MILLIMETERS
A	5.34±0.30
B	6.00±0.30
C	1.05±0.30
D	9.95±0.30
E	0.76±0.15
F	2.28±0.15
G	2.30±0.30
H	1.06±0.30
I	(4-10)°
J	0.51±0.15
K	0.52±0.15
L	0.80±0.30
M	60°
N	(0-10)°
O	0.05±0.05
P	6.60±0.30
Q	25°
R	(4-8.5)°
S	R0.40
T	R0.40
U	0.05±0.05
V	0.05±0.05
W	0.90±0.30
a	1.80±0.30
b	0.75±0.30
c	4.85±0.30
d	5.30±0.30
e	6.90±0.30

# Package Outline TO-251



DIM	MILLIMETERS
A	$5.34 \pm 0.30$
B	$6.00 \pm 0.30$
C	$1.05 \pm 0.30$
D	$11.31 \pm 0.30$
E	$0.76 \pm 0.15$
F	$2.28 \pm 0.15$
G	$2.30 \pm 0.30$
H	$1.06 \pm 0.30$
I	$(4-10)^\circ$
J	$0.51 \pm 0.15$
K	$0.52 \pm 0.15$
L	$0.80 \pm 0.30$
M	$60^\circ$
N	$0.75 \pm 0.30$
O	$1.80 \pm 0.30$
P	$6.60 \pm 0.30$
Q	$4.85 \pm 0.30$
R	$(4-8.5)^\circ$
S	$5.30 \pm 0.30$
T	$6.90 \pm 0.30$
U	$0.05 \pm 0.05$
V	$0.05 \pm 0.05$
W	$1.15 \pm 0.25$
Y	$0.85 \pm 0.25$